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U.S. DEPARTMENT OF COMMERCE  
United States Patent and Trademark Office

SHEET



To the Director of the U.S.

103567074

ched documents or the new address(es) below.

1. Name of conveying party(ies):

Shigeru Yamada

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): June 13, 2009

☒ Assignment ☐ Merger ☐ Change of Name

☐ Security Agreement ☐ Joint Research Agreement

☐ Government Interest Assignment

☐ Executive Order 9424, Confirmatory License

☐ Other

2. Name and address of receiving party(ies)

Name: OKI SEMICONDUCTOR CO., LTD.

Internal Address:

Street Address:

550-1 Higashiasakawa-cho Hachioji-shi

City: Tokyo

State:

Country: JAPAN Zip: 193-8550

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

☒

This document is being filed together with a new application.

A. Patent Application No.(s)

JOINED WAFER, FABRICATION METHOD THEREOF,  
AND FABRICATION METHOD OF SEMICONDUCTOR  
DEVICES

B. Patent No.(s)

Additional numbers attached?

☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Steven M. Rabin  
RABIN & BERDO, PC

Internal Address: Atty. Dkt.: FUJI-219

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Email Address: firm@rabinberdo.com

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

☐ Authorized to be charged to deposit account

☐ Enclosed

☐ None required (government interest not affecting title)

8. Payment Information

Deposit Account Number

Authorized User Name

9. Signature:

Signature

July 1, 2009

Date

Steven M. Rabin - 29,102

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

2

FEE ENCLOSED: \$ 40.00  
Please charge any further fees to  
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07/02/2009 SZEWDIE1 00000047 12458149

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PATENT  
REEL: 022945 FRAME: 0697

**ASSIGNMENT OF APPLICATION FOR UNITED STATES LETTERS PATENT**WHEREAS Shigeru YAMADA

hereinafter referred to collectively as the assignor, has invented a certain improvement relating to JOINED WAFER FABRICATION METHOD THEREOF AND FABRICATION METHOD OF SEMICONDUCTOR DEVICES

[X] the inventor(s) declaration for said application being executed concurrently with the execution of this instrument; said application to be filed in the United States Patent and Trademark Office;

[ ] said application having been filed in the United States Patent and Trademark Office on, \_\_\_\_\_ authorization being hereby given to the practitioners associated with the Customer Number 23995, to insert here in parentheses (Application Serial No. \_\_\_\_\_) the application serial number of said application when known;

[ ] said application having been filed under the Patent Cooperation Treaty on \_\_\_\_\_ Serial No. \_\_\_\_\_, the United States of America being designated.

AND WHEREAS OKI SEMICONDUCTOR CO., LTD.

of 550-1 Higashiasakawa-cho Hachioji-shi, Tokyo 193-8550, Japan

hereinafter referred to as the assignee, is desirous of acquiring the entire right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof;

NOW THIS WITNESSETH, that for and in consideration of One Dollar (\$1.00), and other good and valuable consideration paid by said assignee to said assignor, the receipt of which is hereby acknowledged, said assignor hereby assigns, sells and transfers to said assignee, and said assignee's successors and assigns, the full and exclusive right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof; said assignee, and said assignee's successors and assigns, to have, hold, exercise and enjoy the said application, including any and all divisions and continuations thereof, and the said invention and any and all patents which may be granted therefor, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges and advantages in anywise arising from or appertaining thereto, for and during the term or terms of any and all such patents when granted, including any and all renewals, reissues and prolongations thereof, for the use and benefit of said assignee, and said assignee's successors and assigns, in as ample and beneficial a manner as the said assignor might or could have held and enjoyed the same, if this assignment had not been made.

AND said assignor hereby agrees to perform, upon the request of said assignee, or said assignee's successors or assigns, any and all acts relating to the obtaining or to the asserting of said patents, including any and all renewals, reissues and prolongations thereof.

AND said assignor authorizes and requests the Commissioner of Patents and Trademarks to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said assignee, and said assignee's successors and assigns, in accordance herewith.

AND Assignors hereby grant the following individuals the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document:

Rabin & Berdo, PC

All practitioners at Customer Number 23995.

AND Assignors acknowledge an obligation of assignment of this invention to Assignee at the time the invention was made.

EXECUTED, June 13, 2009

WITNESS:

ASSIGNOR:

Signature: Yu Takeshita

Signature: Shigeru Yamada

Name: Shigeru YAMADA

Rabin & Berdo, PC

PATENT

RECORDED: 07/01/2009

REEL: 022945 FRAME: 0698